

## 19 Fraunhofer project center in Tohoku University



FhG Germany – Sendai city partnership signing ceremony in Munich (July15,2005)



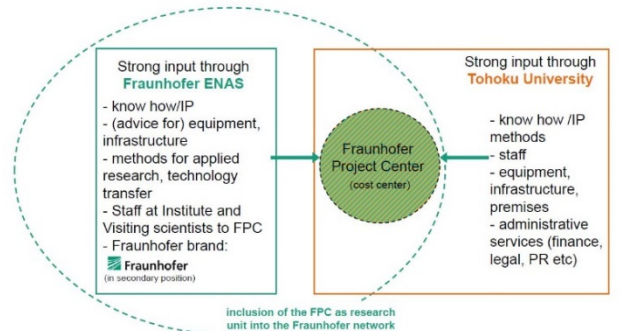
1<sup>st</sup> Fraunhofer Symposium in Sendai (Oct.19, 2005)



FhG Germany – WPI-AIMR Tohoku Univ. partnership signing ceremony in Sendai (Nov. 8, 2011)

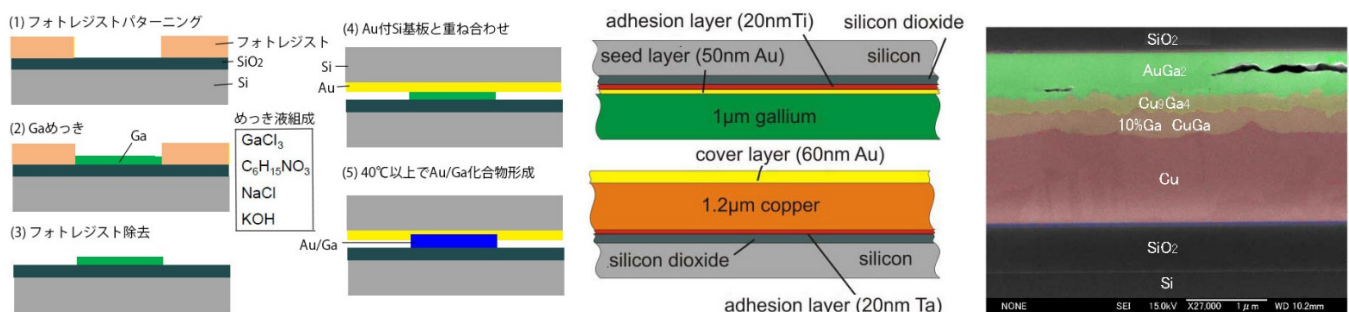
### Fraunhofer Project Center Model

Key aspects of cooperation – Mutual contributions



Assoc. Prof. Joerg .Frömel

FhG Project center in WPI-AIMR, Tohoku Univ. (April 1, 2012)



Low temperature SLID (Solid-Liquid Inter-Diffusion) bonding with Cu- Ga

(J.Froemel et.al. (ENAS, Fh.G), J. of Microelectromechanical Systems, 24 (2015) 1973)

Old method to fill an eroded tooth (amalgam method) (UV curable resin at present)  
Cu powder + Hg → Solidify (Metallic compound)